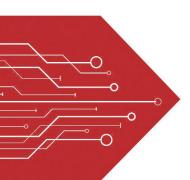
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Brodnet data speet

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Semiconductor

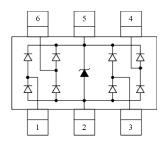
Compiance

PACKAGE OUTLINE



S0T-23-6

PIN CONFIGURATION



FEATURES

♦ Transient protection for high-speed data lines IEC 61000-4-2(ESD) ±20KV(Contact) ±25KV(Air)

IEC 61000-4-4(EFT) 40A(5/50ns)

- ♦ Package optimized for high-speed lines
- ♦ Small package(2.9mm*2.8mm*1.1mm)
- ♦ Protects four data lines and one Vcc line
- ♦ Low capacitance: 0.20pF (I/O to I/O)
- ♦ Low leakage current
- ♦ Low clamping voltage

MACHANICAL DATA

- ♦ Flammability Rating: UL 94V-0
- ♦ Terminal: Matte tin plated.
- ♦ High temperature soldering guaranteed:
- **♦ 260 ℃/10s**
- ♦ Packaging: Tape and Reel
- ♦ Reel size: 7 inch

APPLICATIONS

- ♦ Serial ATA
- ♦ MDDI Ports
- ♦ USB 2.0/3.0 Power and Data Line Protection
- ♦ Display Ports
- ♦ High Definition Multi-Media Interface (HDMI)
- ♦ Digital Visual Interface (DVI)

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ABSOLUTE MAXIMUM RATING				
Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power (8/20µs)	60	W	
V_{ESD}	ESD per IEC 61000-4-2 (Contact)	±20	147	
	ESD per IEC 61000-4-2 (Air)	±25	kV	
T _{OPT}	Operating Temperature	-55/+125	°C	
T _{STG}	Storage Temperature	-55/+150	°C	

ELECTRICAL CHARACTERISTICS (Tamb=25°C)						
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V_{RWM}	Reverse Working Voltage	Any I/O pin to GND			5.0	V
V_{BR}	Reverse Breakdown Voltage	I⊤ = 1mA Any I/O pin to GND	6.0		9.0	V
I _R	Reverse Leakage Current	V _{RWM} = 5V Any I/O pin to GND			1.0	μA
		I_{PP} = 1A, t_p = 8/20µs Any I/O pin to GND			10	V
V_{C}	Clamping Voltage	I_{PP} = 4A, t_p = 8/20µs Any I/O pin to GND			15	V
		I _{PP} = 8A, t _p = 8/20μs Vcc pin to GND			15	V
C _{ESD}	Parasitic Capacitance	V _R = 0V, f = 1MHz Between I/O and I/O		0.20	0.30	pF
		V _R = 0V, f = 1MHz Between I/O and GND		0.45	0.50	pF
		V _R = 0V, f = 1MHz Between Vcc and GND		0.80		pF

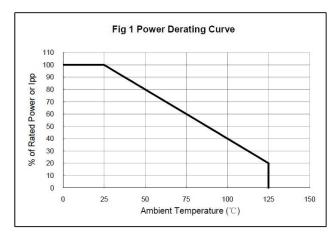
Note: I/O Pins are pin 1,3,4,6. Pin 5 is Vcc. Pin 2 is GND.

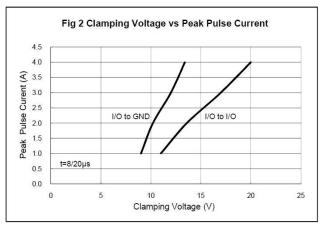


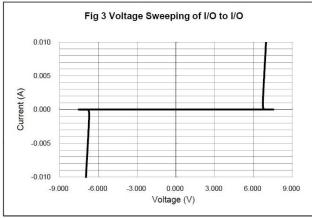
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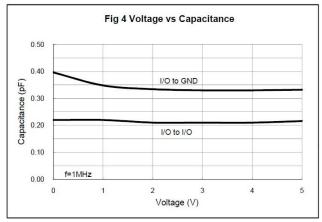


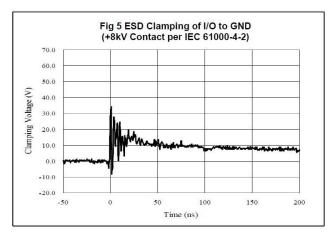
ELECTRICAL CHARACTERISTICS CURVE

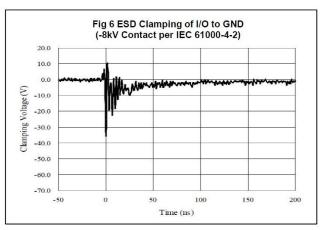






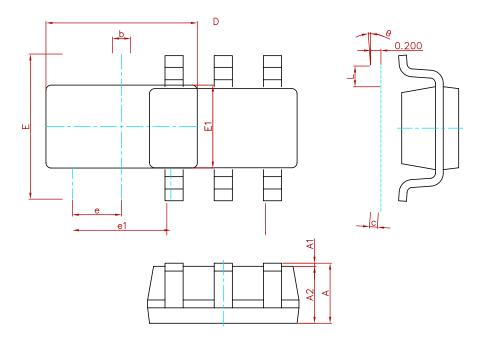






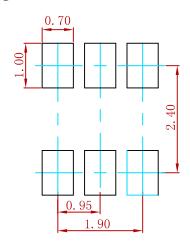


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
E	2.650	2.950	0.104	0.116	
е	0.950(BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESDU5V0H4-MS	SOT-23-6	3000



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